

N0412N

N-CHANNEL MOSFET FOR SWITCHING

R07DS0554EJ0100 Rev.1.00 Nov 07, 2011

Description

The N0412N is N-channel MOS Field Effect Transistor designed for high current switching applications.

Features

• Low on-state resistance

$$R_{DS (on)} = 3.7 \text{ m}\Omega \text{ MAX.} (V_{GS} = 10 \text{ V}, I_D = 50 \text{ A})$$

• Low input capacitance

$$C_{iss} = 5550 \text{ pF TYP.} (V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V})$$

• High current

$$I_{D(DC)} = \pm 100 \text{ A}$$

• RoHS Compliant

Ordering Information

| Part No. | Lead Plating | Packing | Package |
|------------------|---------------|-----------|------------|
| N0412N-S19-AY *1 | Pure Sn (Tin) | Tube | TO-220 |
| | | 50 p/tube | 1.9 g TYP. |

Note: *1. Pb-free (This product does not contain Pb in the external electrode.)

Absolute Maximum Ratings ($T_A = 25^{\circ}C$, all terminals are connected)

| Item | Symbol | Ratings | Unit |
|---|-----------------------|-------------|------|
| Drain to Source Voltage (V _{GS} = 0 V) | V _{DSS} | 40 | V |
| Gate to Source Voltage (V _{DS} = 0 V) | V _{GSS} | ±20 | V |
| Drain Current (DC) | I _{D(DC)} | ±100 | Α |
| Drain Current (pulse) *1 | I _{D(pulse)} | ±400 | Α |
| Total Power Dissipation (T _C = 25°C) | P _{T1} | 119 | W |
| Total Power Dissipation (T _A = 25°C) | P _{T2} | 1.5 | W |
| Channel Temperature | T _{ch} | 150 | °C |
| Storage Temperature | T _{stg} | -55 to +150 | °C |
| Single Avalanche Current *2 | I _{AS} | 55 | Α |
| Single Avalanche Energy *2 | E _{AS} | 300 | mJ |

Thermal Resistance

Channel to Case (Drain) Thermal Resistance $R_{th(ch-C)}$ 1.05 °C/W Channel to Ambient Thermal Resistance *2 $R_{th(ch-A)}$ 83.3 °C/W

Notes: *1. PW \leq 10 μ s, Duty Cycle \leq 1%

*2. Starting T_{ch} = 25°C, R_G = 25 Ω , V_{DD} = 25 V, V_{GS} = 20 \rightarrow 0 V, L = 100 μH

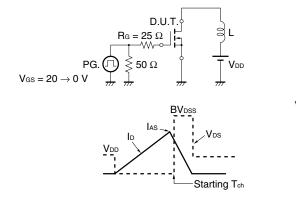
Electrical Characteristics ($T_A = 25$ °C, all terminals are connected)

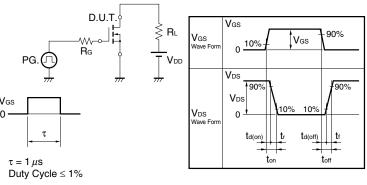
| Item | Symbol | MIN. | TYP. | MAX. | Unit | Test Conditions |
|---|---------------------|------|------|------|------|---|
| Zero Gate Voltage Drain Current | I _{DSS} | | | 1 | μΑ | $V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$ |
| Gate Leakage Current | I_{GSS} | | | ±100 | nA | $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$ |
| Gate to Source Cut-off Voltage | $V_{GS(off)}$ | 2.0 | | 4.0 | V | $V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$ |
| Forward Transfer Admittance *1 | y _{fs} | 26 | | | S | $V_{DS} = 10 \text{ V}, I_{D} = 50 \text{ A}$ |
| Drain to Source On-state Resistance *1 | R _{DS(on)} | | 2.7 | 3.7 | mΩ | V _{GS} = 10 V, I _D = 50 A |
| Input Capacitance | C _{iss} | | 5550 | | pF | $V_{DS} = 25 V$, |
| Output Capacitance | Coss | | 580 | | pF | $V_{GS} = 0 V$, |
| Reverse Transfer Capacitance | C _{rss} | | 320 | | pF | f = 1 MHz |
| Turn-on Delay Time | t _{d(on)} | | 29.0 | | ns | $V_{DD} = 20 \text{ V}, I_D = 50 \text{ A},$ |
| Rise Time | t _r | | 15.0 | | ns | V_{GS} = 10 V , |
| Turn-off Delay Time | $t_{\text{d(off)}}$ | | 64.0 | | ns | $R_G = 0 \Omega$ |
| Fall Time | t _f | | 13.0 | | ns | |
| Total Gate Charge | Q_G | | 100 | | nC | $V_{DD} = 32 V$, |
| Gate to Source Charge | Q_{GS} | | 26 | | nC | V _{GS} = 10 V, |
| Gate to Drain Charge | Q_{GD} | | 32 | | nC | I _D = 100 A |
| Body Diode Forward Voltage *1 | $V_{F(S-D)}$ | | | 1.5 | V | I _F = 100 A, V _{GS} = 0 V |
| Reverse Recovery Time | trr | | 40 | | ns | $I_F = 50 \text{ A}, V_{GS} = 0 \text{ V},$ |
| Reverse Recovery Charge | Qrr | | 44 | | nC | di/dt = 100 A/μs |

Note: *1. Pulsed

TEST CIRCUIT 1 AVALANCHE CAPABILITY

TEST CIRCUIT 2 SWITCHING TIME





TEST CIRCUIT 3 GATE CHARGE

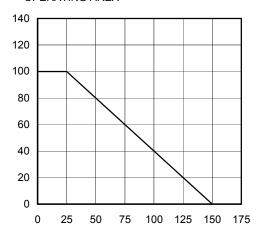
$$\begin{array}{c|c} D.U.T. \\ I_G = 2 \text{ mA} \\ \hline W. & V \end{array}$$

$$\begin{array}{c|c} PG. & \bigcirc \\ \hline \end{array} \begin{array}{c} S50 \ \Omega \\ \hline \end{array} \begin{array}{c} V_{DD} \\ \hline \end{array}$$

dT - Percentage of Rated Power - %

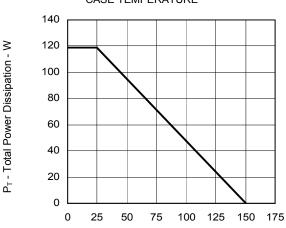
Typical Characteristics ($T_A = 25^{\circ}C$)

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



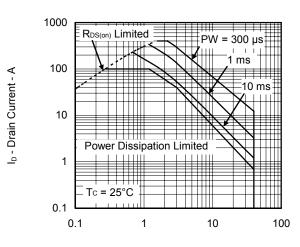
 T_{C} - Case Temperature - $^{\circ}\text{C}$

TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



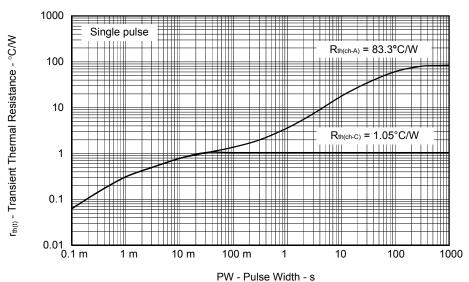
T_C - Case Temperature - °C

FORWARD BIAS SAFE OPERATING AREA



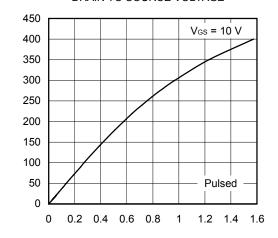
 V_{DS} - Drain to Source Voltage - V

TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



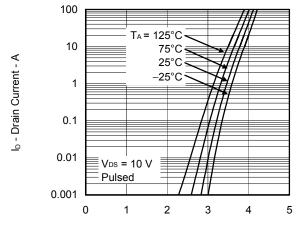
lo - Drain Current - A

DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



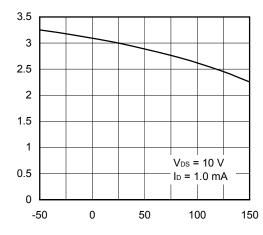
V_{DS} - Drain to Source Voltage - V

FORWARD TRANSFER CHARACTERISTICS



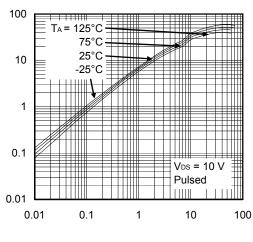
V_{GS} - Gate to Source Voltage - V

GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



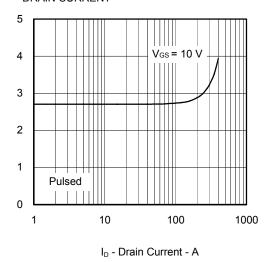
 T_{ch} - Channel Temperature - $^{\circ}C$

FORWARD TRANSFER ADMITTANCE vs. DRAIN **CURRENT**

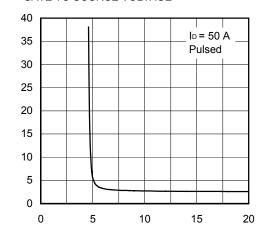


ID - Drain Current - A

DRAIN TO SOURCE ON-STATE RESISTANCE vs. **DRAIN CURRENT**



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



V_{GS} - Gate to Source Voltage - V

 $R_{\text{DS(on)}}$ - Drain to Source On-state Resistance - $m\Omega$

y_s | - Forward Transfer Admittance - S

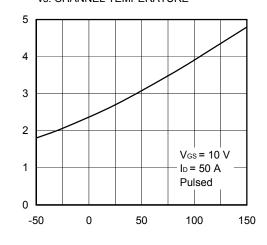
 $R_{\text{DS(on)}}$ - Drain to Source On-state Resistance - $m\Omega$

V_{GS(off)} - Gate to Source Cut-off Voltage - V

 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - Drain to Source On-state Resistance - $m\Omega$

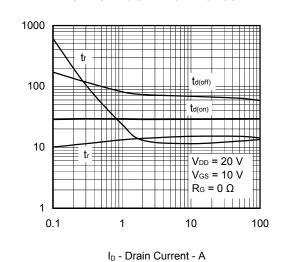
t_{d (on)}, t_r, t_{d (off)}, t_f - Switching Time - ns

DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE

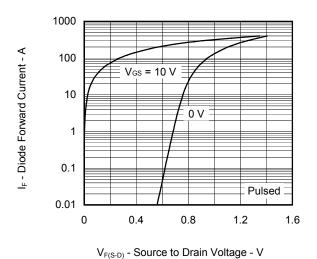


T_{ch} - Channel Temperature - °C

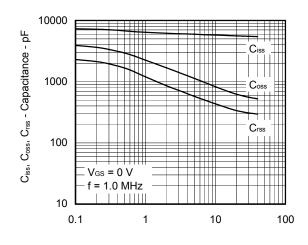
SWITCHING CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE

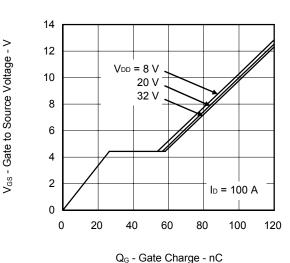


CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

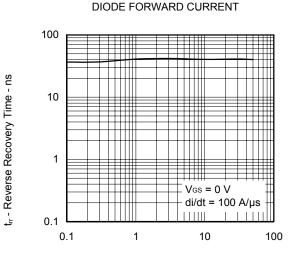


 V_{DS} - Drain to Source Voltage - V

DYNAMIC INPUT CHARACTERISTICS



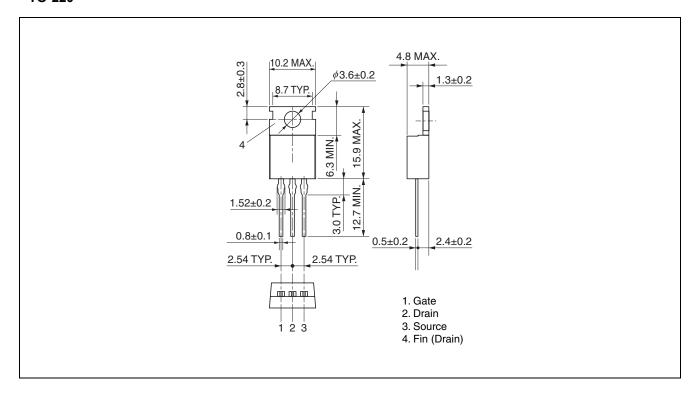
REVERSE RECOVERY TIME vs.



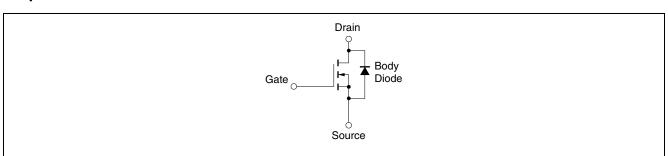
I_F - Diode Forward Current - A

Package Drawing (Unit: mm)

TO-220



Equivalent Circuit



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

Revision History

N0412N Data Sheet

| | | Description | | |
|------|--------------|-------------|----------------------|--|
| Rev. | Date | Page | Summary | |
| 1.00 | Nov 07, 2011 | _ | First Edition Issued | |

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